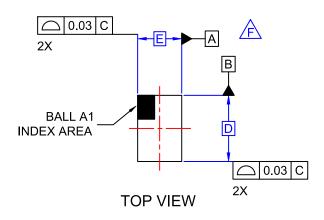
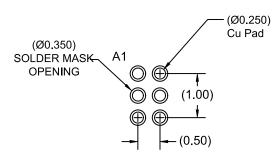
ON

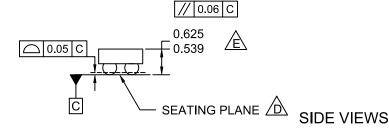
WLCSP6 1.5x1.0x0.582 CASE 567RL ISSUE O

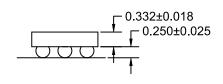
DATE 30 NOV 2016





RECOMMENDED LAND PATTERN (NSMD PAD TYPE)





Ø0.005(₩) C A Ø0.315 +/- .025 6X C 1.00 0.50 B (Y) ±0.018 F (X) ±0.018 BOTTOM VIEW

NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCE PER ASMEY14.5M, 1994.

DATUM C IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.

PACKAGE NOMINAL HEIGHT IS 582 MICRONS ±43 MICRONS (539-625 MICRONS).

F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.

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DESCRIPTION:	WLCSP6 1.5x1.0x0.582		PAGE 1 OF 1

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